

DATE 02 JUL 2007

NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: MILLIMETERS. DIMENSION 6 APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN
- 0.15 AND 0.30mm FROM TERMINAL. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS		
DIM	MIN	NOM	MAX
Α	0.70	0.75	0.80
A1	0.00	0.03	0.05
A3	0.20 REF		
b	0.18	0.24	0.30
D	3.00 BSC		
D2	2.45	2.50	2.55
E	3.00 BSC		
E2	1.75	1.80	1.85
е	0.50 BSC		
K	0.19 TYP		
L	0.35	0.40	0.45

GENERIC MARKING DIAGRAM*



= Assembly Location

L = Wafer Lot = Year Υ = Work Week W = Pb-Free Package

Α

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	WDFN10 3X3, 0.5P		PAGE 1 OF 1	

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